Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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Eight Channel, High Speed, Unipolar, Ultrasound Pulser 1.5A 150V

Features

► HVCMOS technology for high performance
► High density integrated ultrasound transmitter
► 0 to +150V output voltage
► ±1.5A source and sink current (min.)
► ±300mA current in CW mode
► Up to 18MHz operating frequency
► Matched delay times
► Built-in gate driver floating voltage regulator
► 2.5 to 3.3V CMOS logic interface

Application

► Portable medical ultrasound imaging
► Piezoelectric transducer drivers
► NDT ultrasound transmission
► Pulse waveform generator

General Description

The Supertex HV7355 is an eight-channel, unipolar, high voltage, high-speed pulse generator. It is designed for medical ultrasound applications. This high voltage and high speed integrated circuit can also be used for other piezoelectric, capacitive or MEMS sensors in ultrasonic nondestructive detection and sonar ranger applications.

The HV7355 consists of a controller logic interface circuit, level translators, MOSFET gate drivers and high current P-channel and N-channel MOSFETs as the output stage for each channel.

The output stages of each channel are designed to provide peak output currents over ±1.5A for pulsing, when MC = 1, with up to 150V swings. When MC = 0, all the output stages drop the peak current to ±500mA for low-voltage CW mode operation to save power. This direct coupling topology of the gate driver not only saves one high voltage capacitor per channel, but also makes the PCB layout easier.
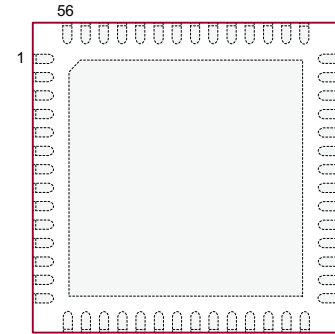
Typical Application Circuit
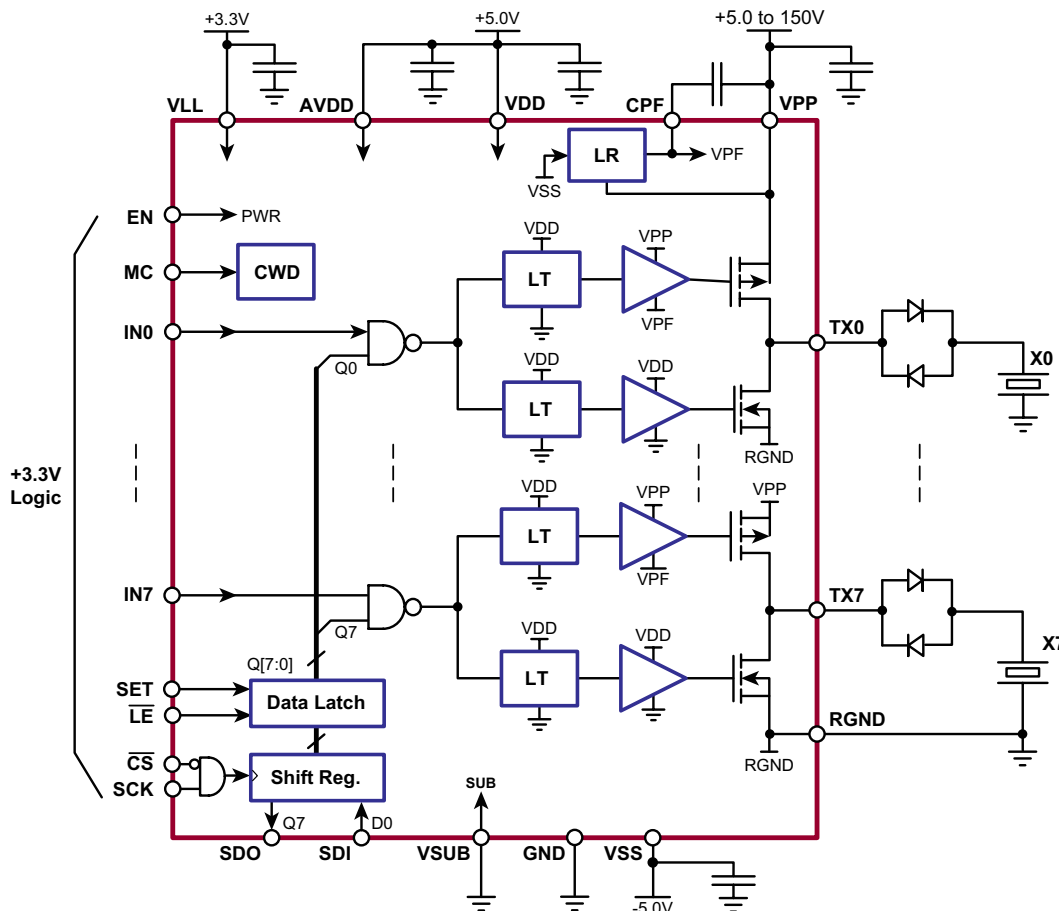
Ordering Information

Part Number	Package Options	Packing
HV7355K6-G	56-Lead QFN (8x8)	250/Tray
HV7355K6-G M937	56-Lead QFN (8x8)	2000/Reel

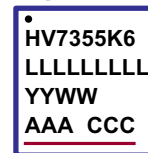*-G denotes a lead (Pb)-free / RoHS compliant package*

ESD Sensitive Device

Absolute Maximum Ratings

Parameter	Value
GND, RGND and V_{SUB}	0V
V_{LL}, Positive logic supply	-0.5V to +7.0V
V_{DD}, Positive logic and level translator supply	-0.5V to +7.0V
V_{SS}, Negative level translator and LR supply	+0.5V to -7.0V
V_{PP}, High voltage positive supply	-0.5V to +160V
(V_{PP} -V_{TXx}) Voltage	-0.5V to +160V
(V_{TXx} - RGND) Voltage	-0.5V to +160V
All logic input PIN_X, NIN_X and EN voltages	-0.5V to +7.0V
Operating temperature	-40°C to 125°C
Storage temperature	-65°C to 150°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

Typical Thermal Resistance

Package	θ_{ja}
56-Lead QFN	21°C/W

Pin Configuration

56-Lead QFN
(top view)

Package Marking

HV7355K6
LLLLLLLLL
YYWW
AAA CCC

L = Lot Number
YY = Year Sealed
WW = Week Sealed
A = Assembler ID
C = Country of Origin
_____ = "Green" Packaging

Package may or may not include the following marks: Si or ⊕

56-Lead QFN

Power-Up Sequence

Step	Description
1	V_{SS}
2	V_{LL} with logic signal low
3	V_{DD}
4	V_{PP}
5	EN & logic signal go to high

Power-Down Sequence

Step	Description
1	EN & logic signal low
3	V_{PP}
4	V_{DD}
5	V_{LL}
6	V_{SS}

Note:
Powering up/down in any arbitrary sequence will not cause any damage to the device. The powering up/down sequence is only recommended in order to minimize possible inrush current.

Truth Table *(MC = X)*

Logic Inputs			Output
EN	Q[7:0]	IN0~7	TX0~7
1	1111,1111	0	GND
1	1111,1111	1	VPP
1	0	X	GND
0	X	X	HiZ

Drive Mode Control Table

MC	I_{SC} (A)	R_{onP}	R_{onN}
0	0.50	18	13
1	1.6	8.0	3.0

Note:
V_{PP} = +150V, V_{DD} = +5.0 V, V_{LL} = +3.3V, V_{SS} = -5.0V, V_{SUB} = 0V

Operating Supply Voltages and Current (Eight Active Channels)

(Operating conditions, unless otherwise specified, V_{LL} = +3.3V, $V_{ADD} = V_{DD}$ = +5.0V, V_{SS} = -5.0V, V_{PP} = +150V, T_A = 25°C)

Sym	Parameter	Min	Typ	Max	Units	Conditions
V_{LL}	Logic voltage reference	2.37	3.30	3.47	V	---
V_{DD}	Internal voltage supply	4.5	5.0	5.5	V	---
V_{PP}	Positive gate driver supply	V_{DD}	-	+150	V	---
V_{SS}	Negative low voltage supply	-5.5	-5.0	-4.5	V	---
V_{PF}	Gate driver floating voltage	-	5.0	-	V	---
I_{LL}	V_{LL} Current EN = Low	-	2.0	10	µA	---
I_{DDQ}	V_{DD} Current EN = Low	-	50	150	µA	f = 0MHz
I_{DDEN}	V_{DD} Current EN = High	-	1.0	4.0	mA	f = 0MHz
I_{DDEN}	V_{DD} Current MC = High	-	160	-	mA	f = 5.0MHz, continuous no loads
I_{DDENCW}	V_{DD} Current MC = Low	-	12	-	mA	
I_{SSQ}	V_{SS} Current EN = Low	-	5.0	20	µA	---
I_{SSEN}	V_{SS} Current EN = High	-	1.0	4.0	mA	f = 0MHz
I_{SSEN}	V_{SS} Current MC = High	-	95	-	mA	f = 5.0MHz, continuous no loads
I_{SSENCW}	V_{SS} Current MC = Low	-	50	-	mA	
I_{PPQ}	V_{PP} Current EN = Low	-	2.0	10	µA	---
I_{PPEN}	V_{PP} Current EN = High	-	200	450	µA	f = 0MHz
I_{PPEN}	V_{PP} Current MC = High	-	370	-	mA	f = 5.0MHz, continuous no loads
I_{PPENCW}	V_{PP} Current MC = Low	-	300	-	mA	

Under Voltage and Over Temperature Protection

Sym	Parameter	Min	Typ	Max	Units	Conditions
V_{UVDD}	V_{DD} threshold	3.4	-	4.4	V	(Internal only)
V_{UVLL}	V_{LL} threshold	-	1.7	-	V	(Internal only)
V_{UVPF}	$V_{PP} - V_{PF}$ threshold	2.5	-	3.8	V	(Internal only)

Logic Inputs

(Operating conditions, unless otherwise specified, V_{LL} = +3.3V, $V_{ADD} = V_{DD}$ = +5.0V, V_{SS} = -5.0V, V_{PP} = +150V, T_A = 25°C)

Sym	Parameter	Min	Typ	Max	Units	Conditions
V_{IH}	Input logic high voltage	$(V_{LL} - 0.4)$	-	V_{LL}	V	---
V_{IL}	Input logic low voltage	0	-	0.4	V	---
I_{IH}	Input logic high current	-	-	1.0	µA	---
I_{IL}	Input logic low current	-1.0	-	-	µA	---
C_{IN}	Input logic capacitance	-	-	5.0	pF	---

Electrical Characteristics

(Operating conditions, unless otherwise specified, V_{LL} = +3.3V, V_{ADD} = V_{DD} = +5.0V, V_{SS} = -5.0V , V_{PP} = +150V, T_A = 25°C)

P-Channel MOSFET Output, TX0~7

Sym	Parameter	Min	Typ	Max	Units	Conditions
I_{OUT}	Output saturation current	1.4	1.6	-	A	MC = 1
R_{ON}	Channel resistance	-	8.0	-	Ω	100mA
I_{OUT}	Output saturation current	0.5	-	-	A	MC = 0
R_{ON}	Channel resistance	-	18	-	Ω	100mA

N-Channel MOSFET Output, TX0~7

Sym	Parameter	Min	Typ	Max	Units	Conditions
I_{OUT}	Output saturation current	1.5	1.7	-	A	MC = 1
R_{ON}	Channel resistance	-	3.0	-	Ω	I_{SD} = 100mA
I_{OUT}	Output saturation current	0.5	-	-	A	MC = 0
R_{ON}	Channel resistance	-	22	-	Ω	100mA

AC Electrical Characteristics

(Operating conditions, unless otherwise specified, V_{LL} = +3.3V, V_{ADD} = V_{DD} = +5.0V, V_{SS} = -5.0V , V_{PP} = +150V, T_A = 25°C)

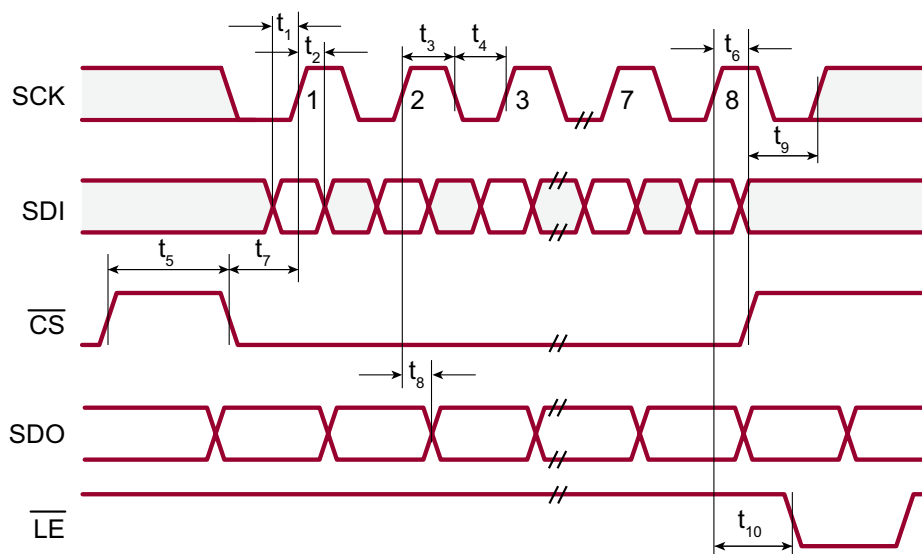| Sym	Parameter	Min	Typ	Max	Units	Conditions
t_{inrf}	Input data rise/fall max time	-	-	10	ns	---
t_r	Output rise time	-	24	-	ns	330pF//2.5kΩ load
t_f	Output fall time	-	24	-	ns	see timing test diagram
f_{OUT}	Output frequency range	-	-	18	MHz	100Ω resistor load, V_{PP} = +90V
t_{EN-ON}	Initial enable time	-	150	200	µs	2µF on each CPF pin to 90% of V_{CPF}
t_{EN-OFF}	Output disable time	-	2.0	5.0	µs	at 5.0MHz CW
t_{dr}	Delay time on inputs rise	-	5.0	-	ns	V_{PP} = 25V
t_{df}	Delay time on inputs fall	-	5.0	-	ns	1.0Ω resistor load, 50% to 50%
t_{dm}	Delay on mode change	-	50	70	ns	see timing test diagram
Δt_{DELAY}	Delay time matching	-	± 2.0	-	ns	P to N, channel to channel
t_j	Delay jitter on rise or fall	-	15	-	ps	---

Serial Data Interface Timing Characteristics

(Operating conditions, unless otherwise specified, V_{LL} = +3.3V, V_{ADD} = V_{DD} = +5.0V, V_{SS} = -5.0V , V_{PP} = +150V, T_A = 25°C)

Sym	Parameter	Min	Typ	Max	Units	Conditions
f_{SCK}	Serial clock max. frequency	25	-	-	MHz	
t_1	SDI valid to SCK setup time	0	2.0	-	ns	
t_2	SDI valid to SCK hold time	4.0	-	-	ns	
t_3	SCK high time	9.0	-	-	ns	All from/to 50% rise or fall edges (See timing diagram)
t_4	SCK low time	9.0	-	-	ns	
t_5	$\overline{CS}$ pulse width	9.0	-	-	ns	
t_6	SCK high to $\overline{CS}$ high	7.0	-	-	ns	
t_7	$\overline{CS}$ low to SCK high	7.0	-	-	ns	
t_8	SDO delay from SCK rise edge	-	6.5	-	ns	SDO with 100pF to GND
t_9	$\overline{CS}$ high to SCK rise edge	7.0	-	-	ns	All from/to 50% rise or fall edges (See timing diagram)
t_{10}	SCK high to $\overline{LE}$ low	7.0	-	-	ns	

Output Timing Test Diagram
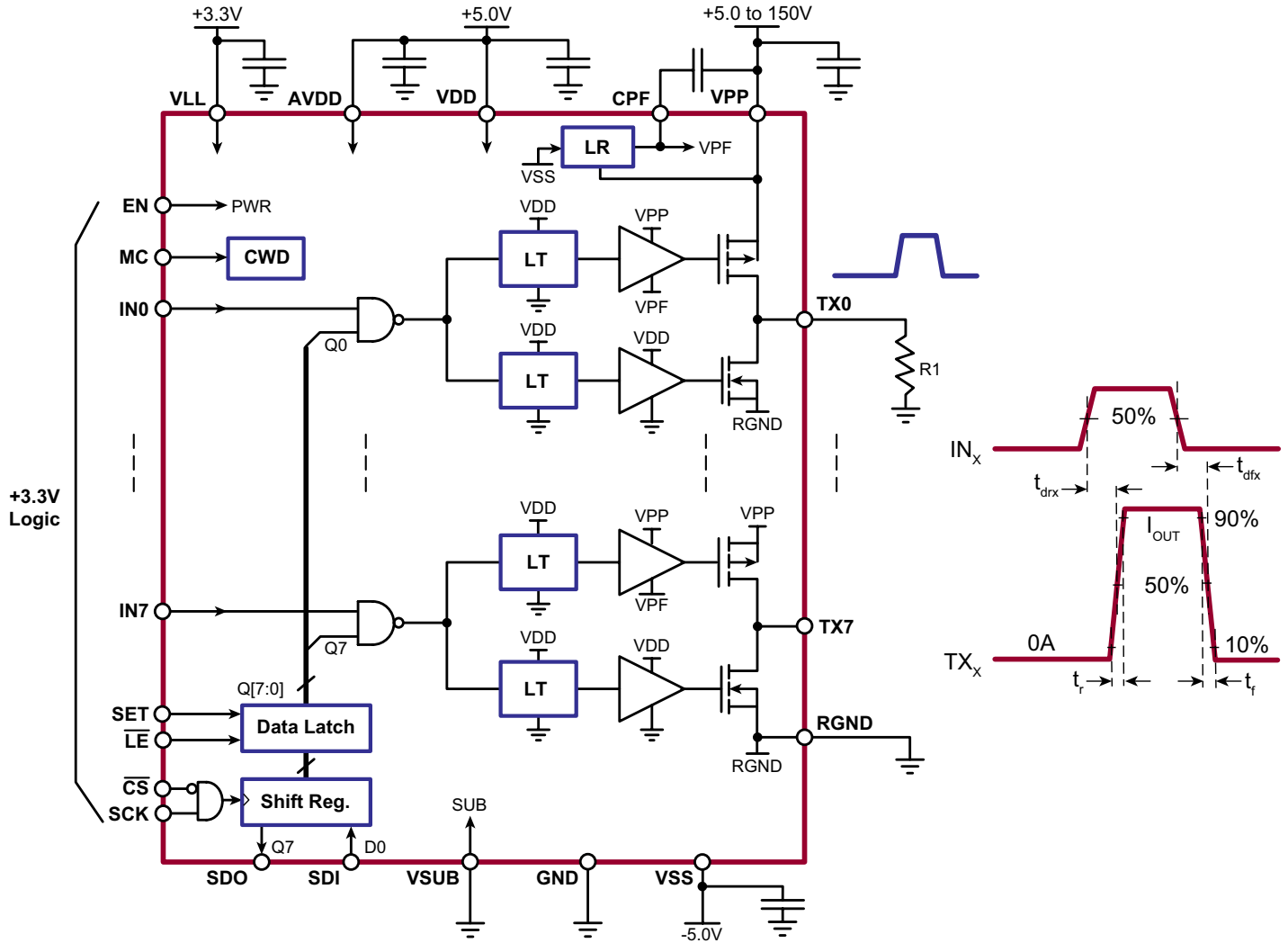
Serial Data Interface Timing Diagram

Pin Description

Pin	Name	Description
1	IN0	
2	IN1	
3	IN2	
4	IN3	Input control for channels 0~7
5	IN4	
6	IN5	
7	IN6	
8	$\overline{\text{IN7}}$	
9	$\overline{\text{CS}}$	Serial interface enable, active low
10	SDI	Serial shift register data input, MSB(D7) first, LSB(D0) last
11	LE	Latch enable, active low
12	SCK	Serial shift register clock
13	SDO	Serial shift register data output
14	SET	Set latch data Q[7:0] = 1, regardless the shift register inputs or LE, active high
15	MC	Output current mode control pin, see Drive Mode Control Table
16	VLL	Logic Hi voltage reference input (+3.3V)
17	VSS	Negative power supply(-5.0V)
18	CPF	Gate driver floating voltage decoupling capacitor to V_{PP}
19	VPP	
20	VPP	Positive high voltage power supply (+150V)
21	VPP	
22	VPP	
23	VDD	Positive voltage supply for gate drivers (+5.0V)
24	RGND	
25	RGND	Output return ground, 0V, RGND pins carry high current, must connect to load transducer
26	RGND	ground
27	RGND	

Pin Description *(cont.)*

| Pin	Name	Description
28	TX7	
29	TX7	
30	TX6	
31	TX6	
32	TX5	
33	TX5	
34	TX4	
35	TX4	Output for channel 0~7
36	TX3	
37	TX3	
38	TX2	
39	TX2	
40	TX1	
41	TX1	
42	TX0	
43	TX0	
44	RGND	
45	RGND	Output return ground, 0V, RGND pins carry high current, must connect to load transducer ground
46	RGND	
47	RGND	
48	VDD	Positive voltage supply for gate drivers (+5.0V)
49	VPP	
50	VPP	Positive high voltage power supply (+150V)
51	VPP	
52	VPP	
53	CPF	Gate driver floating voltage decoupling capacitor to V_{PP}
54	GND	Logic input reference ground, 0V
55	AVDD	Positive internal voltage supply (+5.0V)
56	EN	Chip power enable, active high
VSUB (Thermal Pad)		Substrate bottom is internally connected to the central thermal pad on the bottom of package. It must be connected to GND (0V) externally

56-Lead QFN Package Outline (K6)
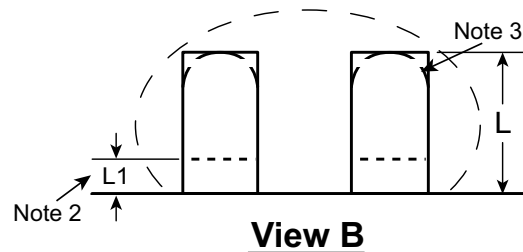## 8.00x8.00mm body, 1.00mm height (max), 0.50mm pitch
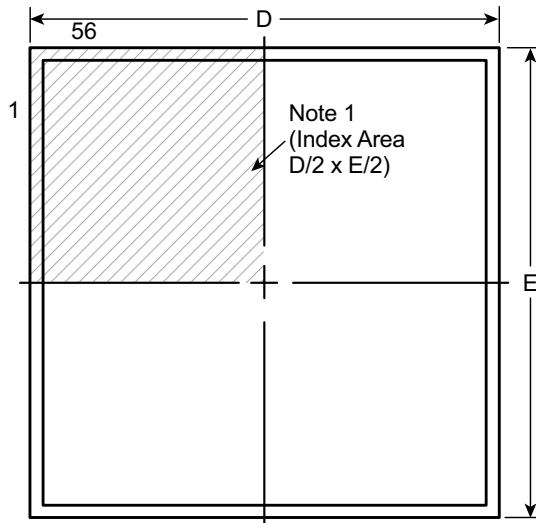
Top View
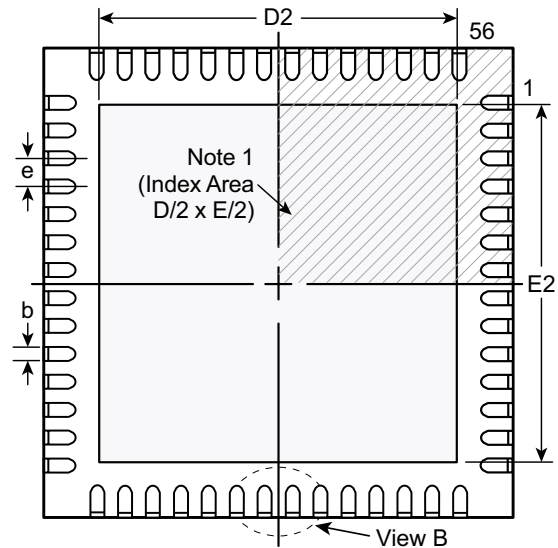
Bottom View
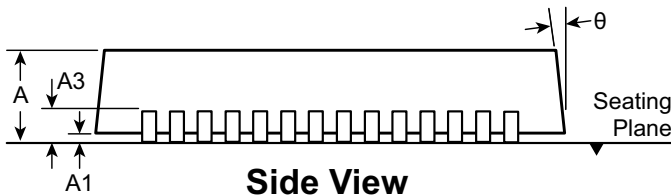
Side View

View B

Notes:

1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.
2. Depending on the method of manufacturing, a maximum of 0.15mm pullback (L1) may be present.
3. The inner tip of the lead may be either rounded or square.

Symbol		A	A1	A3	b	D	D2	E	E2	e	L	L1	θ
Dimension (mm)	MIN	0.80	0.00	0.20 REF	0.18	7.85*	2.75	7.85*	2.75	0.50 BSC	0.30	0.00	0°
	NOM	0.90	0.02		0.25	8.00	5.70	8.00	5.70		0.40	-	-
	MAX	1.00	0.05		0.30	8.15*	6.70†	8.15*	6.70†		0.50	0.15	14°

JEDEC Registration MO-220, Variation VLLD-2, Issue K, June 2006.
* This dimension is not specified in the JEDEC drawing.
† This dimension differs from the JEDEC drawing.
Drawings are not to scale.
Supertex Doc.#: *DSPD-56QFNK68X8P050, Version A031010.*

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to http://www.supertex.com/packaging.html.)

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